

FSS106-TL-E-VB Datasheet P-Channel 30-V (D-S) MOSFET

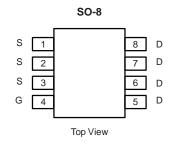
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.018 at V _{GS} = - 10 V	- 9.0	13 nC		
- 30	0.024 at V _{GS} = - 4.5 V	- 7.8	13110		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- 100 % R_g Tested

APPLICATIONS

- Load Switch
- Battery Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \text{ °C}$, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	- 30	V			
Gate-Source Voltage	V _{GS}	± 20	v			
	T _C = 25 °C		- 9.0			
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C		- 7.2			
Continuous Drain Current $(1) = 150$ C)	T _A = 25 °C		- 7.0 ^{a, b}			
	T _A = 70 °C		- 5.6 ^{a, b}	A		
Pulsed Drain Current	I _{DM}	- 30				
Continuous Source-Drain Diode Current	T _C = 25 °C	L.	- 3.5			
Continuous Source-Drain Diode Current	T _A = 25 °C	Is –	- 2.1 ^{a, b}			
	T _C = 25 °C		4.2			
Maximum Davias Disais sties	T _C = 70 °C	р	2.7	w		
Maximum Power Dissipation	T _A = 25 °C	P _D –	2.5 ^{a, b}	vv		
	T _A = 70 °C	1	1.6 ^{a, b}			
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	0/00	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 95 °C/W.

d. Based on $T_C = 25 \text{ °C}$.



HALOGEN

Available

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	-					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050		- 31		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 \text{ °C}$			- 1 - 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 20			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -7.0 \text{ A}$ $V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5.6 \text{ A}$		0.018 0.024		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S
Dynamic ^b						<u> </u>
Input Capacitance	C _{iss}			1455		pF
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		180		
Reverse Transfer Capacitance	C _{rss}			145		
Total Gate Charge	Qg	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 7.0 A		25 13	38 20	
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 7.0 A		3.5		nC
Gate-Drain Charge	Q _{gd}			5.5		
Gate Resistance	R _q	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 2.7 Ω		13	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 5.6 A, V_{GEN} = - 10 V, R_g = 1 Ω		23	35	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			38	57	ns
Rise Time	t _r	V_{DD} = - 15 V, R_L = 2.7 Ω		89	134	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 5.6 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		22	33	
Fall Time	t _f			11	17	
Drain-Source Body Diode Characteris	stics					
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 6.5	A
Pulse Diode Forward Current	I _{SM}				- 30	
Body Diode Voltage	V _{SD}	$I_{S} = -5.6 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 5.6 A, dl/dt = 100 A/µs, T _J = 25 °C		17	26	nC
Reverse Recovery Fall Time	t _a	$F = -3.0 \text{ A}, \text{ and } F = 100 \text{ A/} \text{m}^{-3}, \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3} \text{m}^{-3$		13		ns
Reverse Recovery Rise Time	t _b			9		

Notes:

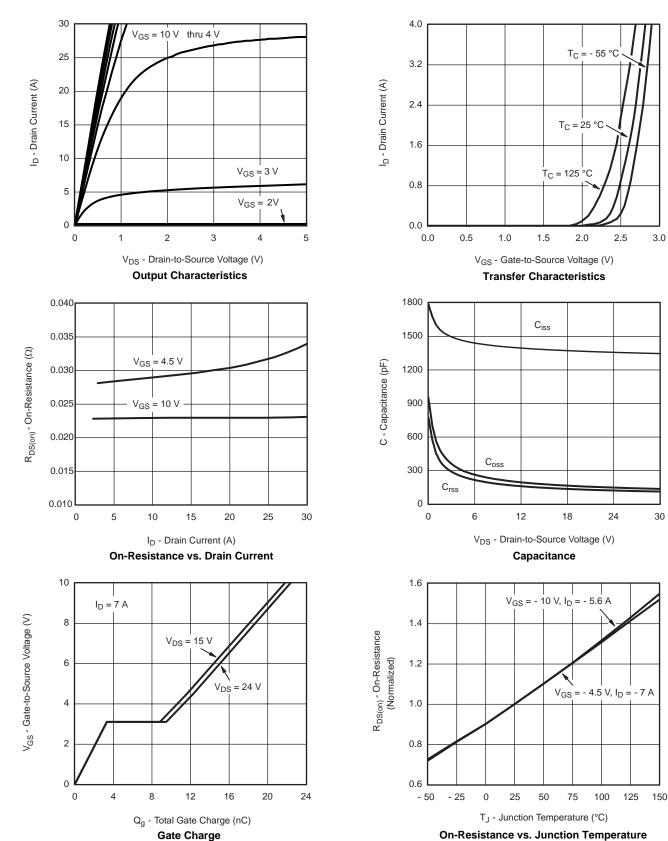
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

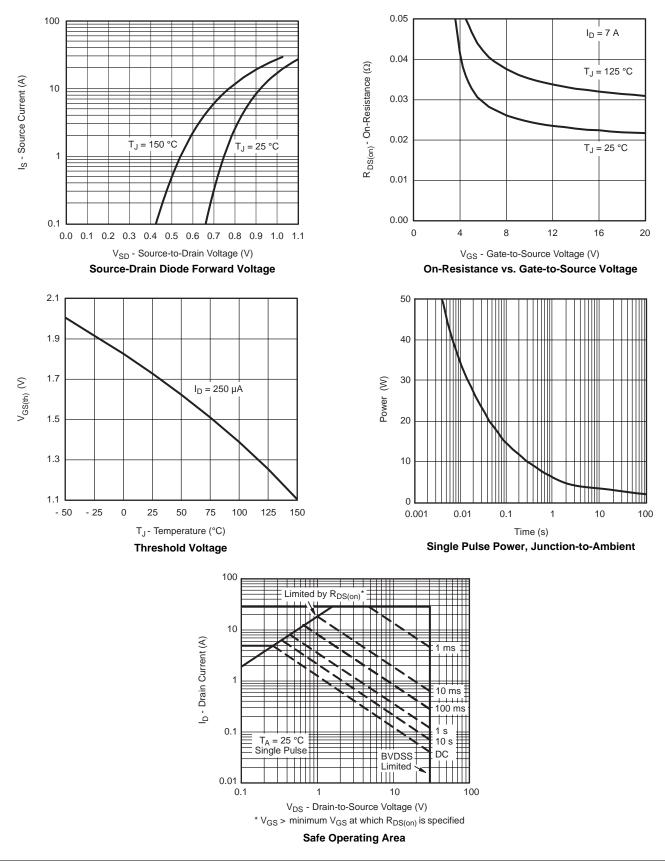
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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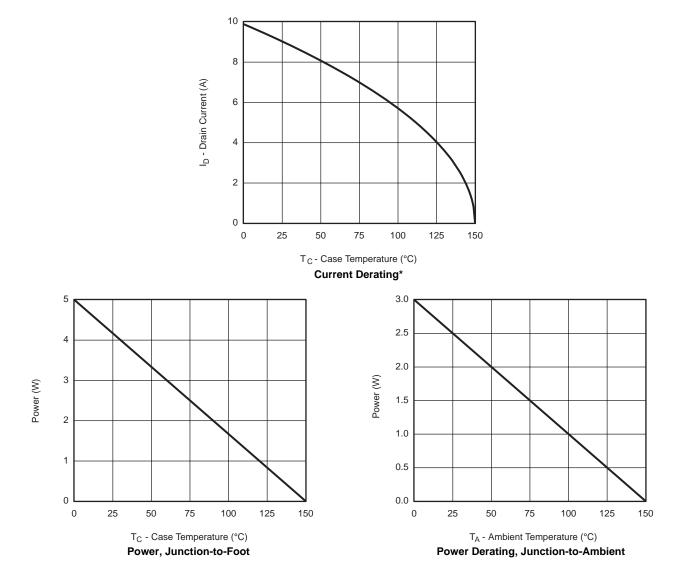






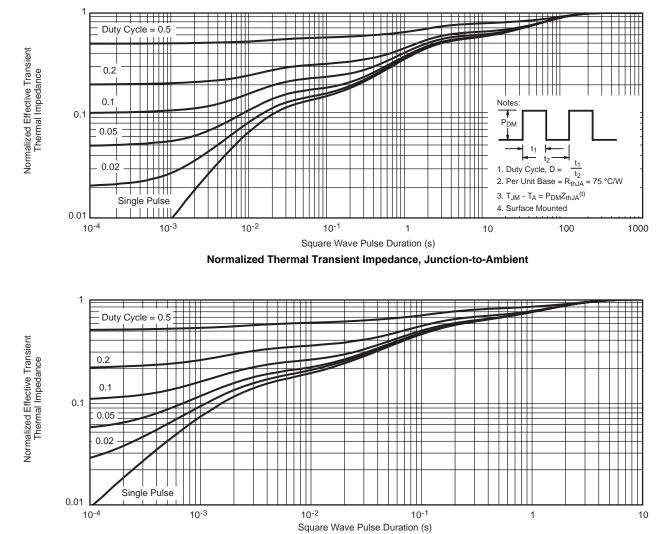






* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

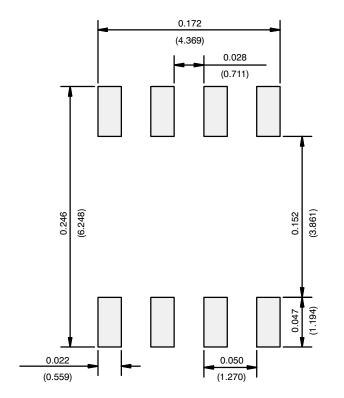




	MILLIMETERS		INC	HES		
DIM	Min	Max	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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